

Title (en)

METHOD AND APPARATUS FOR DELIVERING POWER TO HIGH PERFORMANCE ELECTRONIC ASSEMBLIES

Title (de)

VERFAHREN UND GERÄT ZUR STROMVERSORGUNG EINER ELEKTRONISCHEN HOCHLEISTUNGSBAUGRUPPE

Title (fr)

PROCEDE ET APPAREIL POUR FOURNIR DU COURANT A DES ENSEMBLES ELECTRONIQUES HAUTE PERFORMANCE

Publication

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Application

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Abstract (en)

[origin: WO0167512A2] A method, apparatus, and article of manufacture for providing power from a first circuit board having a first circuit board first conductive surface and a first circuit board second conductive surface to a second circuit board having a second circuit board first conductive surface and a second circuit board second conductive surface is described. The apparatus comprises a first conductive member, including a first end having a first conductive member surface electrically coupleable to the first circuit board first conductive surface and a second end distal from the first end having a first conductive member second surface electrically coupleable to the second circuit board first surface. The apparatus also comprises a second conductive member, having a second conductive member first surface electrically coupleable to the first circuit board second surface and a second conductive member second surface distal from the second conductive member first surface electrically coupleable to the second circuit board second conductive surface.

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